503176482 02/12/2015

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT3223096

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ching-Wen Hung	02/11/2015
Jia-Rong Wu	02/11/2015
Yi-Hui Lee	02/11/2015
Chih-Sen Huang	02/11/2015
Yi-Wei Chen	02/11/2015

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14620212

CORRESPONDENCE DATA

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 3027291562

Email: Patent.admin.uspto.cr@naipo.com

Correspondent Name: WINSTON HSU
Address Line 1: P.O.BOX 506

Address Line 4: MERRIFIELD, VIRGINIA 22116

ATTORNEY DOCKET NUMBER:	NAUP2400USA
NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	02/12/2015

Total Attachments: 10 source=2178600#page1.tif source=2178600#page2.tif source=2178600#page3.tif

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Title of Invention: **SEMICONDUCTOR STRUCTURE**

As the below named inventor, I here This declaration is directed to:	by declare that:					
☑ The attached application, or						
☐ United States application number filed			n	, or		
☐ PCT international application	n number	filed	d on	Manager and the second		
The above-identified application was	made or authorized to be m	ade by me.	***************************************			
I believe that I am the original invent application.	or or an original joint inventor	r of a claimed	l invention in	the		
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr	I false statement made in this isonment of not more than fiv	s declaration /e (5) years, (is punishable or both.	3		
In consideration of the payment by	UNITED MICROELECTI CORP.	RONICS	having a po	stal address of		
No.3, Li-Hsin Road 2, Science	-Based Industrial Park,	Hsin-Chu	City 300, T	aiwan, R.O.C		
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	o I of the sum of One Dollar (\$ d valuable consideration.	\$ 1.00), the re	eceipt of whi	ch is hereby		
I hereby sell, assign and transfer to A the entire right, title and interest in ar invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all improvemen tion and, in and to, all Letters any continuations, continuat ad as to Letters Patent any re	its which are Patent to be ion-in-part, d issue or re-e	disclosed in obtained for ivisions, renexamination the	the r said ewals, nereof.		
I hereby covenant that no assignmer entered into which would conflict with	nt, sale, agreement or encuml n this assignment;	brance has b	een or will b	e made or		
I further covenant that ASSIGNEE wand documents relating to said invention to I and will te related thereto and will promptly executed.	tion and said Letters Patent a stify as to the same in any int	and legal equ terference, lit	ivalents as r	nav he		
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	lication, said invention and sa cessary or desirable to carry	aid Letters Pa	atent and sai ses thereof.	d (Date of signing		
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire nventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>						

Page 1 of 10

F#NPO-P0002E-US1201

Inventor: Ching-Wen Hung

Signature: Ching - Wen Hung

Date: FEB 1 1 2015

Page 2 of 10

NPO#NAU-P2400-USA:0 CUST#UMCD-2014-0590

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:					
☑ The attached application, or						
☐ United States application nu	mber	filed o	on	, or		
☐ PCT international application	n number	file	d on	***************************************		
The above-identified application was	made or authorized to	be made by me.	***************************************			
I believe that I am the original inventapplication.	or or an original joint in	ventor of a claime	d invention in	1 the		
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impri	I false statement made isonment of not more th	in this declaration an five (5) years,	is punishab or both.	le		
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	l of the sum of One Do d valuable consideratio	ollar (\$ 1.00), the i n.	eceipt of wh	ich is hereby		
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	nd to any and all improvition and, in and to, all L any continuations, continuati	ements which are etters Patent to be linuation-in-part	disclosed in obtained for the contract of the	the r said		
l hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or er this assignment;	ncumbrance has l	oeen or will b	e made or		
further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal						
representatives any and all papers, ir maintain, issue and enforce said appl equivalents thereof which may be ned N WINTNESS WHEREOF, I have he	lication, said invention a cessary or desirable to	and said Letters P carry out the prop	atent and sa	id : (Date of signing)		
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire nventive entity, must accompany this form. Use this form for each additional inventor.						

Page 3 of 10

Inventor: Jia-Rong Wu

Date: FEB 1 1 2015

Signature: Tign Rong Wu

Page 4 of 10

Title of Invention: SEMICONDUCTOR STRUCTURE

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☐ United States application nu	mber	filed	on	, or	
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The above-identified application was	made or authorized to be ma	ade by me.	***************************************		
I believe that I am the original inventapplication.	or or an original joint inventor	of a claime	d invention in	the	
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I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, and thereby seven and that he accions	d to any and all improvemention and, in and to, all Letters any continuations, continuations to Letters Patent any rei	ts which are Patent to be on-in-part, c ssue or re-e	disclosed in the obtained for divisions, renewant the contraction of the contraction the contraction of the	the said ewals, iereof.	
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or encumb this assignment;	orance has t	oeen or will be	e made or	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, in maintain, issue and enforce said appl equivalents thereof which may be neo N WINTNESS WHEREOF, I have he	ication, said invention and sa sessary or desirable to carry o	id Letters P out the prop	atent and said oses thereof.	d (Date of signing)	
Note: An application data sheet (PTO nventive entity, must accompany this	/SB/14 or equivalent), includi form. Use this form for <u>each</u>	ng naming t additional ir	he entire oventor.		

Page 5 of 10

LEGAL NAME OF INVENTORIASSIGNORY					
Inventor:	Yi-Hui Lee		Date:	FEB 1 1 2015	
Signature:	Yi Hui	Lee			

Page 6 of 10

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:				
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The above-identified application was	s made or authorized to be made	by me.	***************************************		
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	ol of the sum of One Dollar (\$ 1.0				
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuations	hich are disclo ent to be obtain in-part division	osed in the ined for said		
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WINTNESS WHEREOF, I have hereunto set hand and seal thisFEB1					
Note: An application data sheet (PTC inventive entity, must accompany this	D/SB/14 or equivalent), including a soften. Use this form for each add	naming the ent	tire or.		

Page

F#NPO-P0002E-US1201

Inventor: Chih-Sen Huang

Date: FEB 1 1 2015

Signature: With-Sen Huang

Page 8 of 10

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	filed on	, or
☐ PCT international application	number	filed c	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original inventor	or or an original joint inventor of	a claimed in	vention in the
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	I false statement made in this de isonment of not more than five (5	claration is postion is postion is consistent to the contract of the contract	punishable ooth.
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	of the sum of One Dollar (\$ 1.6		
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	id to any and all improvements with in and, in and to, all Letters Pai any continuations, continuationd as to Letters Patent any reissu	vhich are dis tent to be ob in-part, divis ie or re-exar	sclosed in the otained for said sions, renewals, mination thereof.
I hereby covenant that no assignmen entered into which would conflict with	t, sale, agreement or encumbrar this assignment;	ice has bee	n or will be made or
I further covenant that ASSIGNEE will and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	tion and said Letters Patent and stify as to the same in any interfe	legal equiva erence, litiga	ilents as may he
representatives any and all papers, in maintain, issue and enforce said appl equivalents thereof which may be ned N WINTNESS WHEREOF, I have he	ication, said invention and said L cessary or desirable to carry out	etters Pate	nt and said es thereof.
Note: An application data sheet (PTO nventive entity, must accompany this	/SB/14 or equivalent), including form. Use this form for each add	naming the ditional inve	entire ntor.

Page 9 of 10

F#NPO-P0002E-US1201 DSC0-103U011138

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Yi-Wei Chen	Date:	FEB 1 1	2015
Signature:	- Yi-Wei chen			

Page 10 of 10

NPO#NAU-P2400-USA:0 CUST#UMCD-2014-0590

RECORDED: 02/12/2015

F#NPO-P0002E-US1201 DSC0-103U011138